

IN THE CLAIMS

Please amend Claim 1 as follows: Attached hereto is Appendix B showing the changes to Claim 1; language that has been added is shown underlined.

1. (Twice amended) A semiconductor package comprising:

a semiconductor die having a first and second sides, a first electrical terminal being located on the first side, at least a second electrical terminal being located on the second side; and

a leadframe in electrical contact with the first terminal, the leadframe being formed in the shape of a cup, the die being located in the cup, at least one lead of the leadframe containing a portion that is coplanar with the second side of the die, and the at least one lead being in electrical contact with the second electrical terminal, the first side of the die facing in a direction toward the inside of the cup.

Please add new Claim 9:

--9. The semiconductor package of Claim 1, wherein the portion of the one lead of the leadframe that is coplanar with the second side of the die extends laterally to be coplanar.--

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